Package Material Composition and Mass Calculation

Package: QFP 208L 28x28
Die Size: 206X205x20 mils

	name	composition	%	mg.	mg.	%	PPM
Mold Compound	Sumitomo G700A				4777.3	88.03	880,349
		Silica Fused	75~95	4060.71		74.830	748,296
		Epoxy Resin	5~10	358.30		6.603	66,026
		Phenol resin	3~8	262.75		4.842	48,419
		Carbon Black	0.1~0.5	14.33		0.264	2,641
Leadframe	CLIN 7025				562.1	10.36	103,573
		Cu	96.20	540.69		9.964	99,638
		Ni	3.00	16.86		0.311	3,107
		Si	0.65	3.65		0.067	673
		Mg	0.15	0.84		0.016	155
Die	Silicon	Silicon			32.2	0.59	5,943
Die Attach	Ablestik 2288A				2.5	0.05	461
		Di-ester resin	5-10	0.19		0.003	35
		Functionalized ester resin	1-5	0.08		0.001	14
		Polymeric material	1-5	0.08		0.001	14
		Metal oxide	1-5	0.08		0.001	14
		Functionalized urethane resin	1-5	0.08		0.001	14
		Epoxy resin	1-5	0.08		0.001	14
		Aromatic compound	1-5	0.08		0.001	14
		Silver	60-100	2.00		0.037	369
Wire	99.99% Au wire				8	0.15	1,474
		Au	99.99	8.00		0.147	1,474
		Ion Impurities	0.01	0.0008		0.000	0.1
External Plating	Solder Plate				44.5	0.8200	8,200
		Sn	98	43.61		0.804	8,036
		Cu	2	0.89		0.016	164
Total					5426.6	100.00	1000000